



SOT2102-1

HVQFN72, thermal enhanced very thin quad flat package, no leads, 72 terminals, 0.5 mm pitch, 10 mm x 10 mm x 0.85 mm body

25 November 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN72
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-03-2014
Manufacturer package code	MV-A300562-00

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.85	10	10.15	mm
package width	9.85	10	10.15	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	72	-	



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2 Package outline

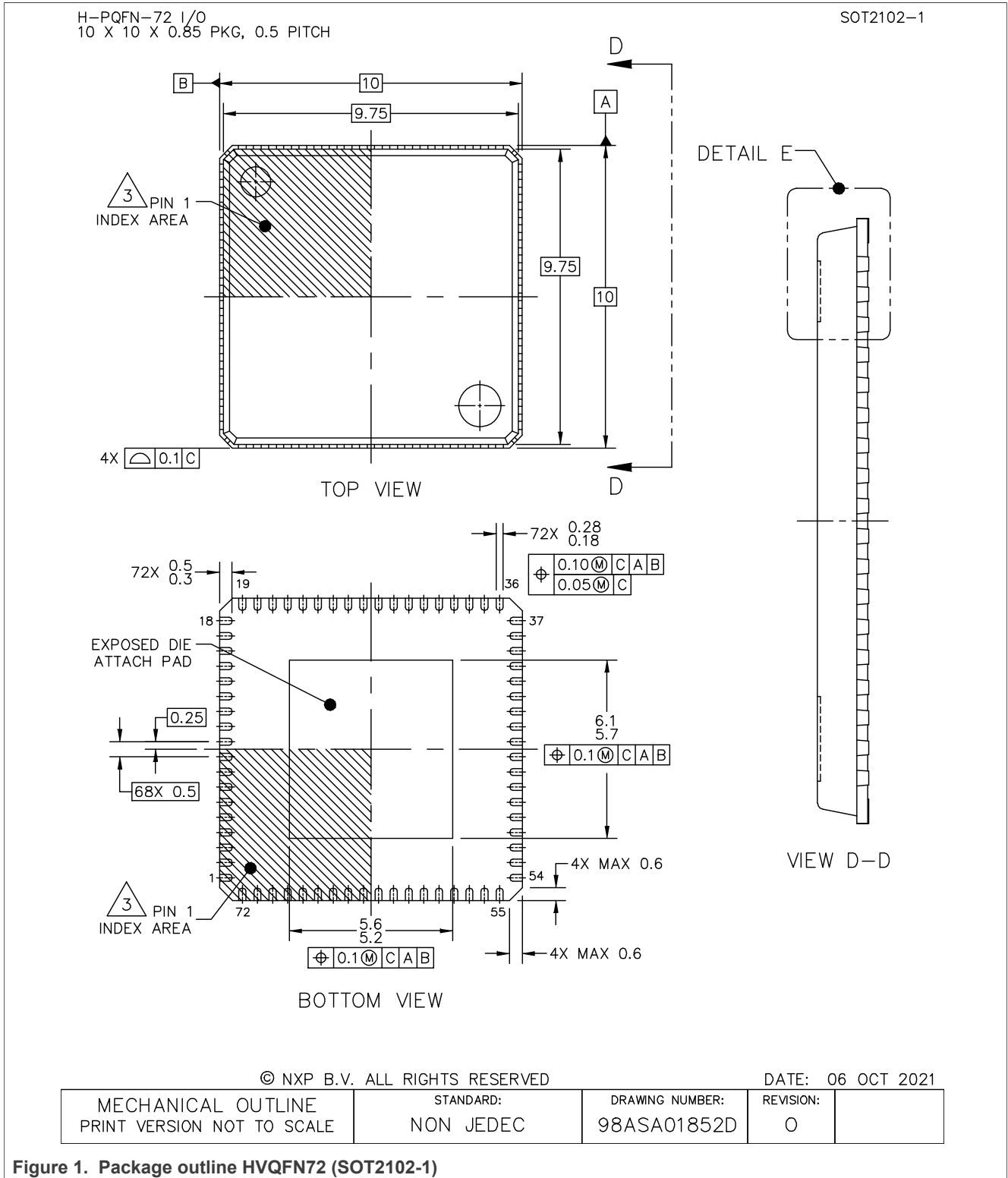
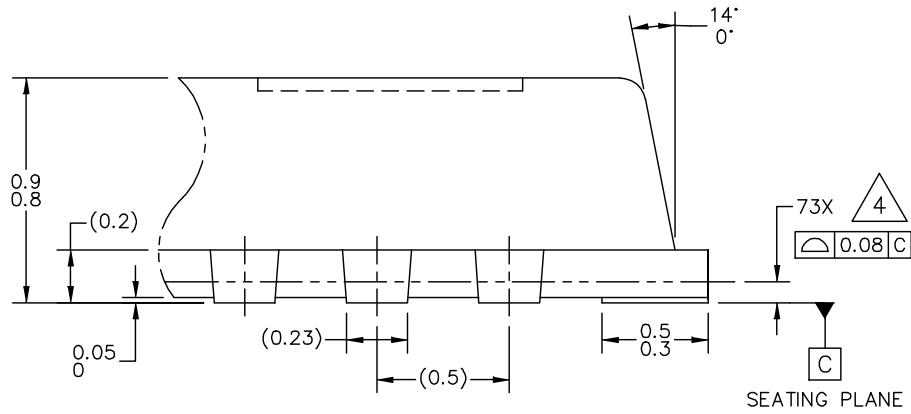


Figure 1. Package outline HVQFN72 (SOT2102-1)

HVQFN72, thermal enhanced very thin quad flat package, no leads, 72 terminals, 0.5 mm pitch, 10 mm x 10 mm x 0.85 mm body

H-PQFN-72 I/O
10 X 10 X 0.85 PKG, 0.5 PITCH

SOT2102-1



DETAIL E
VIEW ROTATED 90° CW

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Figure 2. Package outline detail HVQFN72 (SOT2102-1)

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3 Soldering

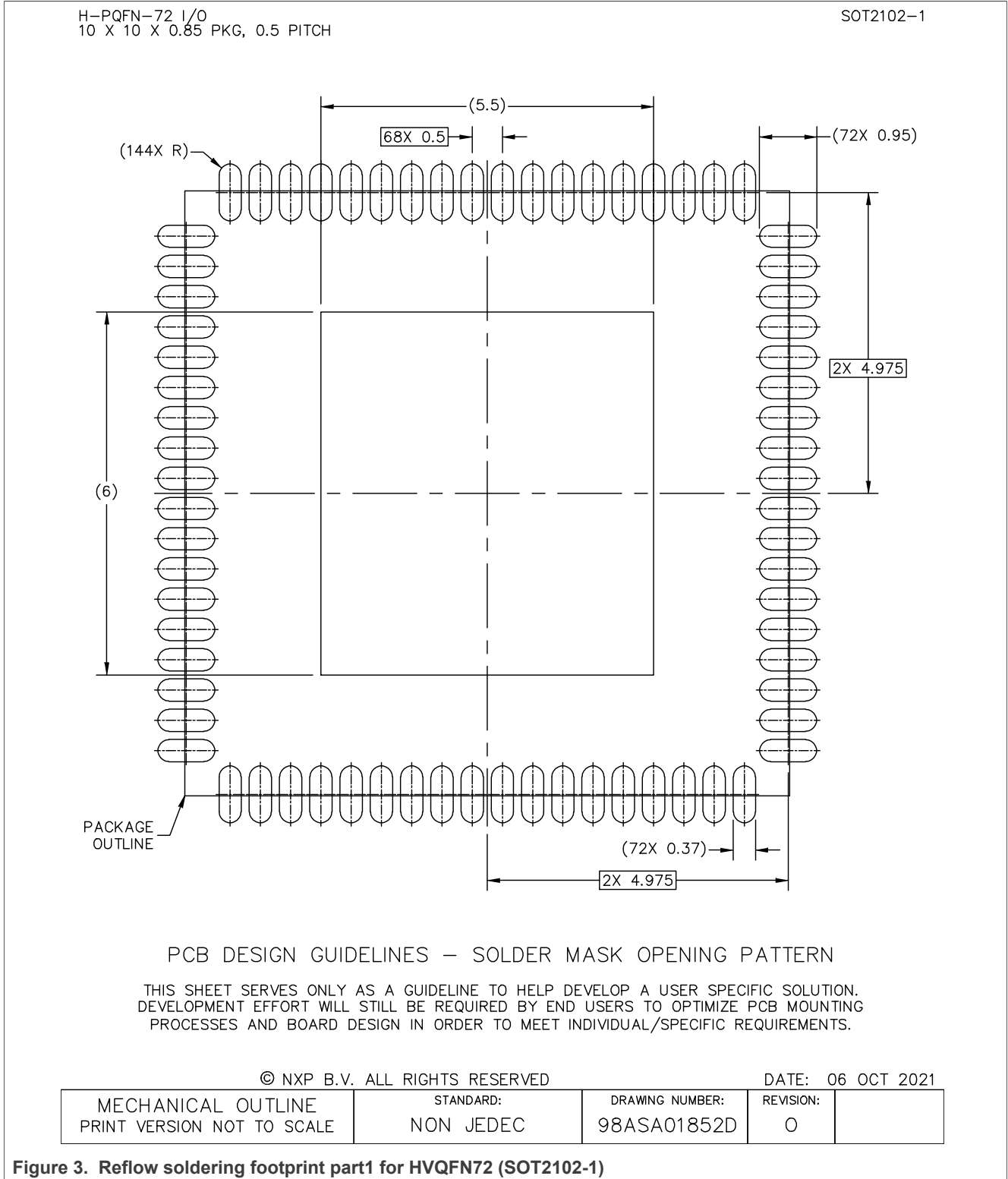


Figure 3. Reflow soldering footprint part1 for HVQFN72 (SOT2102-1)

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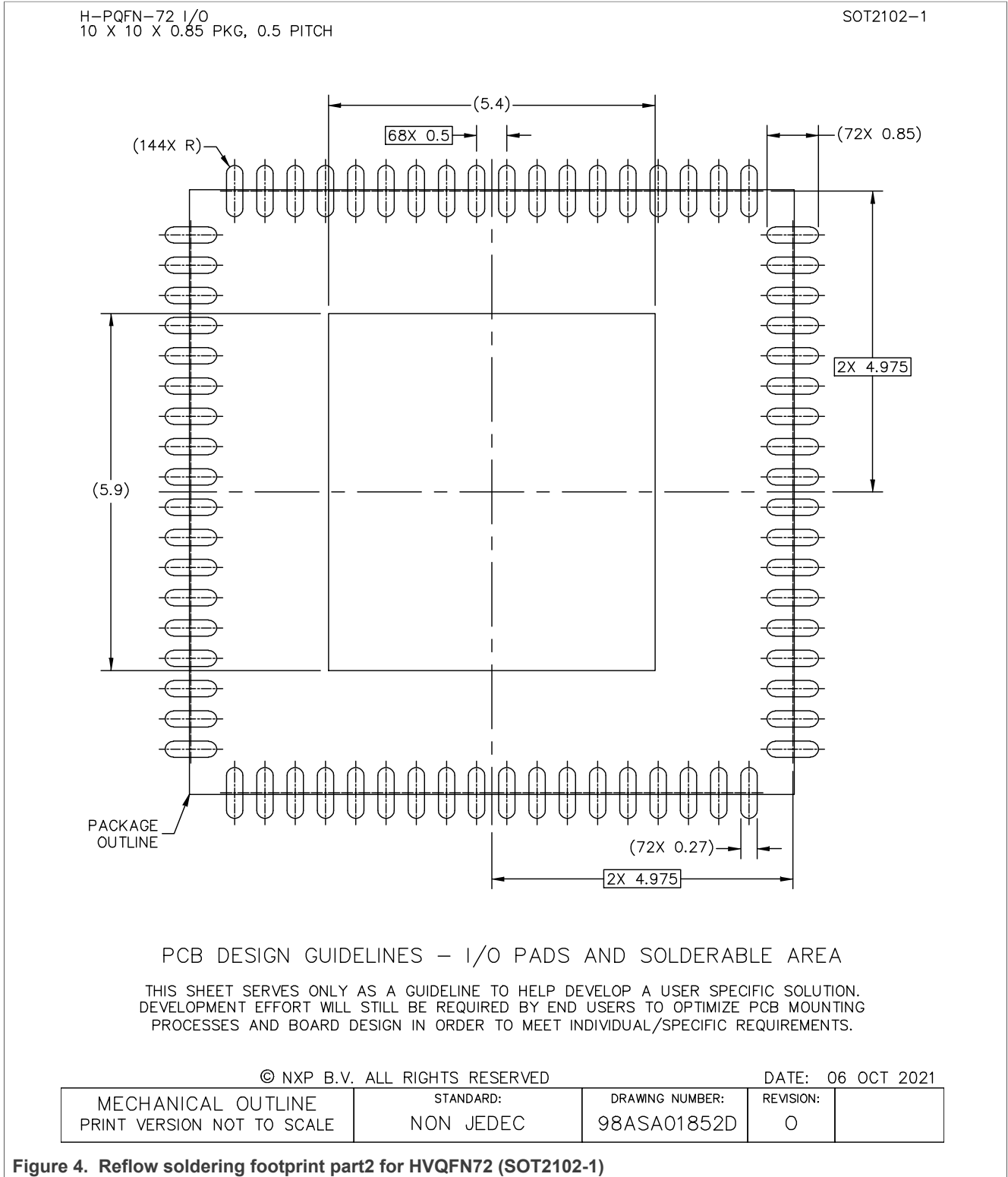
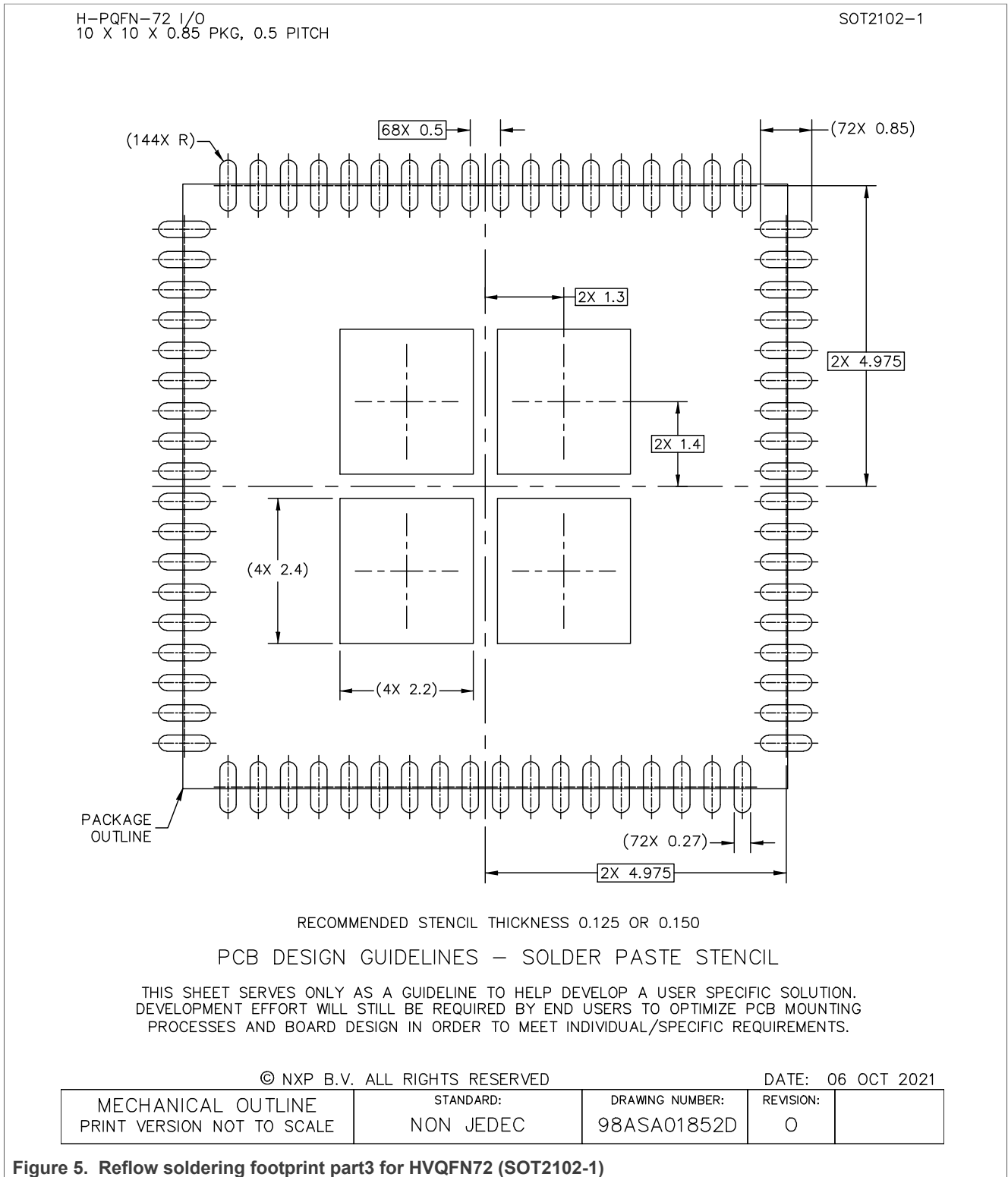


Figure 4. Reflow soldering footprint part2 for HVQFN72 (SOT2102-1)

HVQFN72, thermal enhanced very thin quad flat package, no leads, 72 terminals, 0.5 mm pitch, 10 mm x 10 mm x 0.85 mm body



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H-PQFN-72 I/O
10 X 10 X 0.85 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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Figure 6. Package outline note HVQFN72 (SOT2102-1)

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4 Legal information

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